

# **Description**

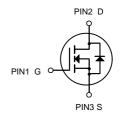
The Si2302ADS uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

# D. S. G.

#### SOT-23

### **General Features**

 $V_{DS} = 20V I_{D} = 2.3 A$   $R_{DS(ON)} < 60 m\Omega @ V_{GS} = 4.5 V$ 



#### N-Channel MOSFET

# **Application**

Battery protection

Load switch

Uninterruptible power supply

**Package Marking and Ordering Information** 

Product ID	Pack	Brand	Qty(PCS)
Si2302ADS	SOT-23	HXY MOSFET	3000

# Absolute Maximum Ratings (T<sub>A</sub>=25 ℃ unless otherwise noted)

Parameter	Limit	Unit
Drain-Source Voltage	20	V
Gate-Source Voltage	±12	V
Drain Current-Continuous	2.3	A
Drain Current-Pulsed (Note 1)	16	A
Maximum Power Dissipation	0.9	W
Operating Junction and Storage Temperature Range	-55 To 150	${\mathbb C}$
Thermal Resistance,Junction-to-Ambient (Note 2)	139	°C/W
	Drain-Source Voltage  Gate-Source Voltage  Drain Current-Continuous  Drain Current-Pulsed (Note 1)  Maximum Power Dissipation  Operating Junction and Storage Temperature Range	Drain-Source Voltage 20  Gate-Source Voltage ±12  Drain Current-Continuous 2.3  Drain Current-Pulsed (Note 1) 16  Maximum Power Dissipation 0.9  Operating Junction and Storage Temperature Range -55 To 150



# Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

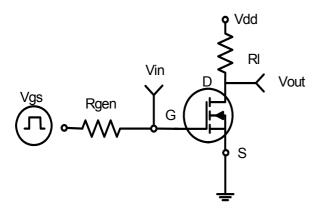
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	20	22	-	V
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> =20V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	Igss	V <sub>GS</sub> =±12V,V <sub>DS</sub> =0V	-	-	±100	nA
Gate Threshold Voltage	V <sub>G</sub> S(th)	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	0.5	0.75	1.2	V
	_	V <sub>GS</sub> =2.5V, I <sub>D</sub> =2.0A	-	54	72	mΩ
Drain-Source On-State Resistance	RDS(ON)	V <sub>GS</sub> =4.5V, I <sub>D</sub> =2.3A	-	48	60	mΩ
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =5V,I <sub>D</sub> =2.3A	-	8	-	S
Input Capacitance	C <sub>lss</sub>		-	260	-	PF
Output Capacitance	Coss	V <sub>DS</sub> =10V,V <sub>GS</sub> =0V,	-	48	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0MHz	-	27	-	PF
Turn-on Delay Time	td(on)		-	2.5	-	nS
Turn-on Rise Time	tr	V <sub>DD</sub> =10V, R <sub>L</sub> =3.3Ω	-	3.2	-	nS
Turn-Off Delay Time	td(off)	$V_{GS}$ =4.5V, $R_{GEN}$ =6 $\Omega$	-	21	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	3	-	nS
Total Gate Charge	Qg		-	2.9	5	nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> =10V,I <sub>D</sub> =2.3A,	-	0.4	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> =4.5V	-	0.6	-	nC
Diode Forward Voltage (Note 3)	VsD	V <sub>GS</sub> =0V,I <sub>S</sub> =2.3A	-	0.75	1.2	V
Diode Forward Current (Note 2)	Is		-	-	3.3	Α

#### Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production



# **Typical Electrical and Thermal Characteristics**



**Figure 1:Switching Test Circuit** 

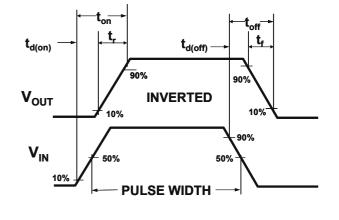
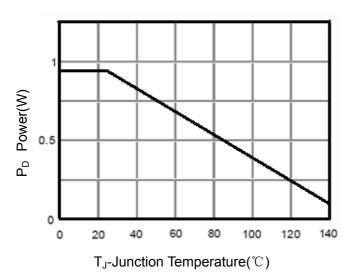
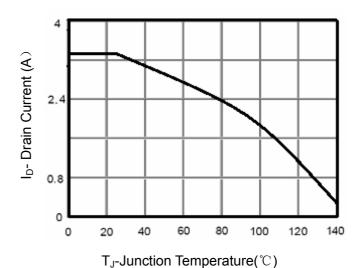


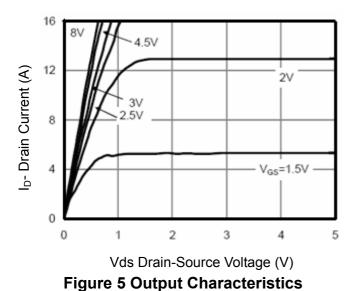
Figure 2:Switching Waveforms



**Figure 3 Power Dissipation** 



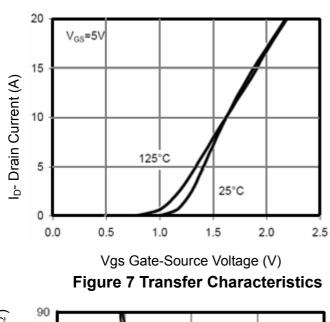
**Figure 4 Drain Current** 

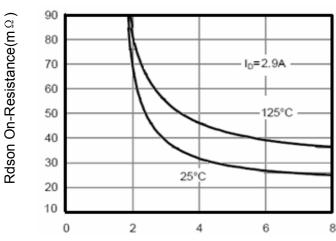


100

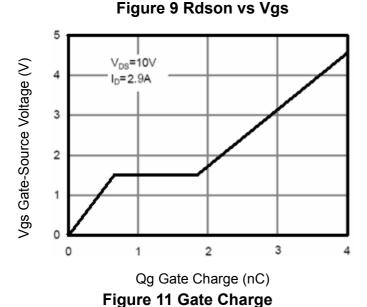
I<sub>D</sub>- Drain Current (A) Figure 6 Drain-Source On-Resistance

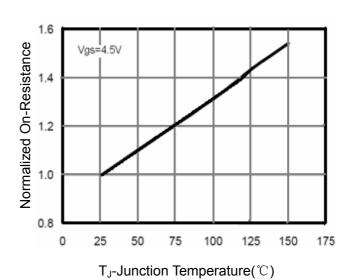


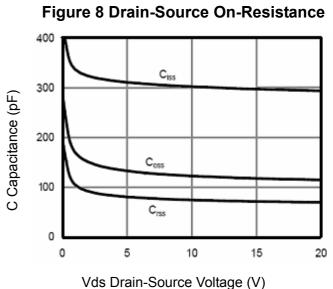


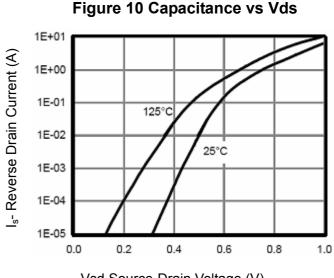


Vgs Gate-Source Voltage (V)





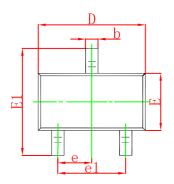


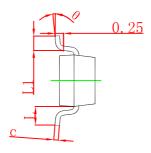


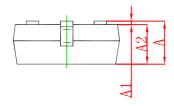
Vsd Source-Drain Voltage (V)
Figure 12 Source- Drain Diode Forward



# **SOT-23 Package Outline Dimensions**

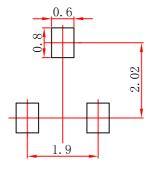






Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950	TYP	0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

# **SOT-23 Suggested Pad Layout**



- Note:
  1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
  3.The pad layout is for reference purposes only.



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